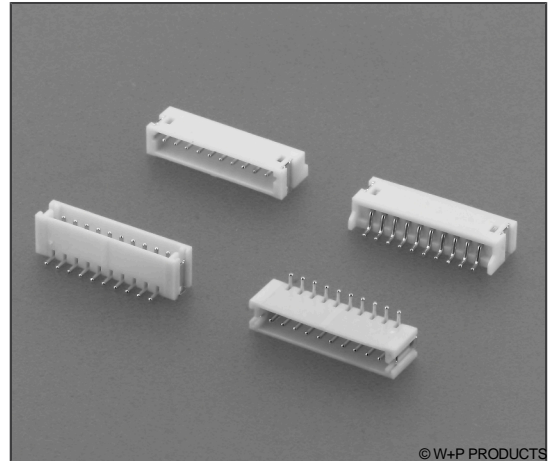


SMT-Crimp-Rast-Stiftleisten RM 1,50mm, stehend/liegend, 1-reihig SMT Friction Lock Pin Headers, 1.50mm Pitch, Vertical/Horizontal, Single Row

Technische Daten / Technical Data

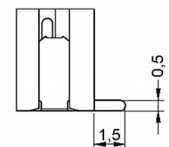
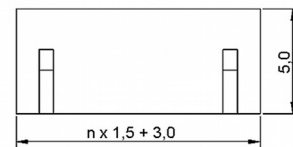
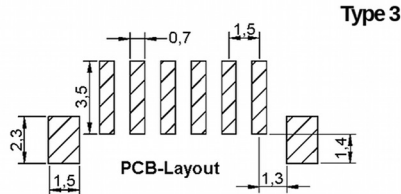
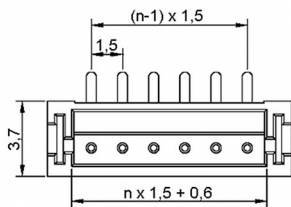
Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Rundstift 0,50mm, Kupferlegierung <i>Round pin 0.50mm, Copper alloy</i>
Aderquerschnitt <i>Applicable wire Gauge</i>	AWG 32 ~ 28 <i>AWG 32 ~ 28</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ <i>< 20 mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 500 MΩ <i>> 500 MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC <i>500 V AC</i>
Nennspannung <i>Voltage Rating</i>	100 V AC <i>100 V AC</i>
Nennstrom <i>Current Rating</i>	1 A <i>1 A</i>
Temperaturbereich <i>Temperature Range</i>	-25 °C ... +85 °C <i>-25 °C ... +85 °C</i>
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>



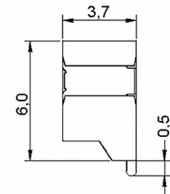
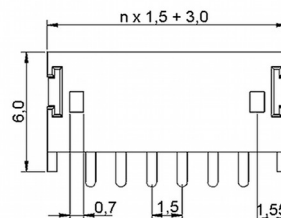
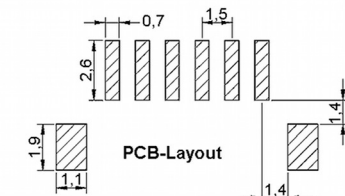
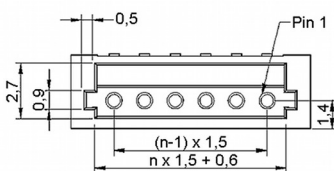
© W+P PRODUCTS

Passende Buchsengehäuse Serien:
Compatible Housing Series:

569



Type 3



Type 4

Series

5690

Contacts*

06

02-13

Type*

3

3 Stiftleiste stehend
Vertical pin header
4 Stiftleiste liegend
Horizontal pin header

Plating

50

50 Verzinkt
Tin plated

Packaging*

ST

ST
TR (Option)
FTR (Option)

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / *In tubes w/o Pick&Place Pads*
TR (Option) Tape & Reel ohne P&P-Pads / *Tape & Reel w/o P&P Pads*
FTR (Option) Tape & Reel mit P&P-Film-Pads / *Tape & Reel with P&P Film Pads*

Informationen zum Reflow-Lötverfahren Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	217 °C
Duration above T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

